

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6303358

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
AKIRA DOI	08/06/2020
MINORU SASAKI	08/06/2020
MASAKI HASEGAWA	08/14/2020
HIRONORI OGAWA	08/19/2020
TOMOHIKO OGATA	08/19/2020
YUKO OKADA	08/21/2020
RECEIVING PARTY DATA	
Name:	HITACHI HIGH-TECH CORPORATION
Street Address:	17-1, TORANOMON 1-CHOME, MINATO-KU,
City:	TOKYO
State/Country:	JAPAN
Postal Code:	1056409
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16981769
CORRESPONDENCE DATA	
Fax Number:	(703)684-1157
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	703-684-1120
Email:	svannarath@mmpiaw.com
Correspondent Name:	MATTINGLY & MALUR, PC
Address Line 1:	1800 DIAGONAL ROAD
Address Line 2:	SUITE 210
Address Line 4:	ALEXANDRIA, VIRGINIA 22314
ATTORNEY DOCKET NUMBER:	H&A-12790
NAME OF SUBMITTER:	JOHN R. MATTINGLY
SIGNATURE:	/John R. Mattingly/
DATE SIGNED:	09/17/2020

Total Attachments: 6

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ASSIGNMENT
(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI HIGH-TECH CORPORATION, a corporation organized under the laws of Japan, located at 17-1, Toranomon 1-chome, Minato-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI HIGH-TECH CORPORATION, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

WAFER INSPECTION APPARATUS AND WAFER INSPECTION METHOD

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, No.PCT/JP2018/020719 filed 30 May 2018, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI HIGH-TECH CORPORATION, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI HIGH-TECH CORPORATION,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Akira Doi</u> Akira DOI	<u>Aug. 06. 2020</u>
2) _____ Minoru SASAKI	_____
3) _____ Masaki HASEGAWA	_____
4) _____ Hironori OGAWA	_____
5) _____ Tomohiko OGATA	_____
6) _____ Yuko OKADA	_____
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1)	_____ Akira DOI	_____
2)	_____ <i>Minoru Sasaki</i> _____ Minoru SASAKI	_____ <i>Aug. 06, 2020</i> _____
3)	_____ Masaki HASEGAWA	_____
4)	_____ Hironori OGAWA	_____
5)	_____ Tomohiko OGATA	_____
6)	_____ Yuko OKADA	_____
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3) <u>Masaki Hasegawa</u> Masaki HASEGAWA	8 / 14 / 2020
4) _____ Hiromori OGAWA	_____
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3)	_____	_____
	Masaki HASEGAWA	
4)	<i>Hironori Ogawa</i> _____	<i>Aug. 19, 2020</i> _____
	Hironori OGAWA	
5)	_____	_____
	Tomohiko OGATA	
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